

74HC257; 74HCT257

Quad 2-input multiplexer; 3-state

Rev. 6 — 26 January 2015

Product data sheet

1. General description

The 74HC257; 74HCT257 are high-speed Si-gate CMOS devices and are pin compatible with Low-power Schottky TTL (LSTTL).

The 74HC257 and 74HCT257 have four identical 2-input multiplexers with 3-state outputs, which select 4 bits of data from two sources and are controlled by a common data select input (S).

The data inputs from source 0 (1I0 to 4I0) are selected when input S is LOW and the data inputs from source 1 (1I1 to 4I1) are selected when S is HIGH. Data appears at the outputs (1Y to 4Y) in true (non-inverting) form from the selected inputs.

The 74HC257 and 74HCT257 are the logic implementation of a 4-pole, 2-position switch, where the position of the switch is determined by the logic levels applied to S. The outputs are forced to a high-impedance OFF-state when $\overline{OE}$ is HIGH.

The logic equations for the outputs are:

$$1\bar{Y} = \overline{OE} \cdot (1I1 \cdot S \cdot 1I0 \cdot \bar{S})$$

$$2\bar{Y} = \overline{OE} \cdot (2I1 \cdot S \cdot 2I0 \cdot \bar{S})$$

$$3\bar{Y} = \overline{OE} \cdot (3I1 \cdot S \cdot 3I0 \cdot \bar{S})$$

$$4\bar{Y} = \overline{OE} \cdot (4I1 \cdot S \cdot 4I0 \cdot \bar{S})$$

Except for their non-inverting (true) outputs the 74HC257; 74HCT257 are identical to the 74HC258.

2. Features and benefits

- Non-inverting data path
- 3-state outputs interface directly with system bus
- Complies with JEDEC standard no. 7A
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

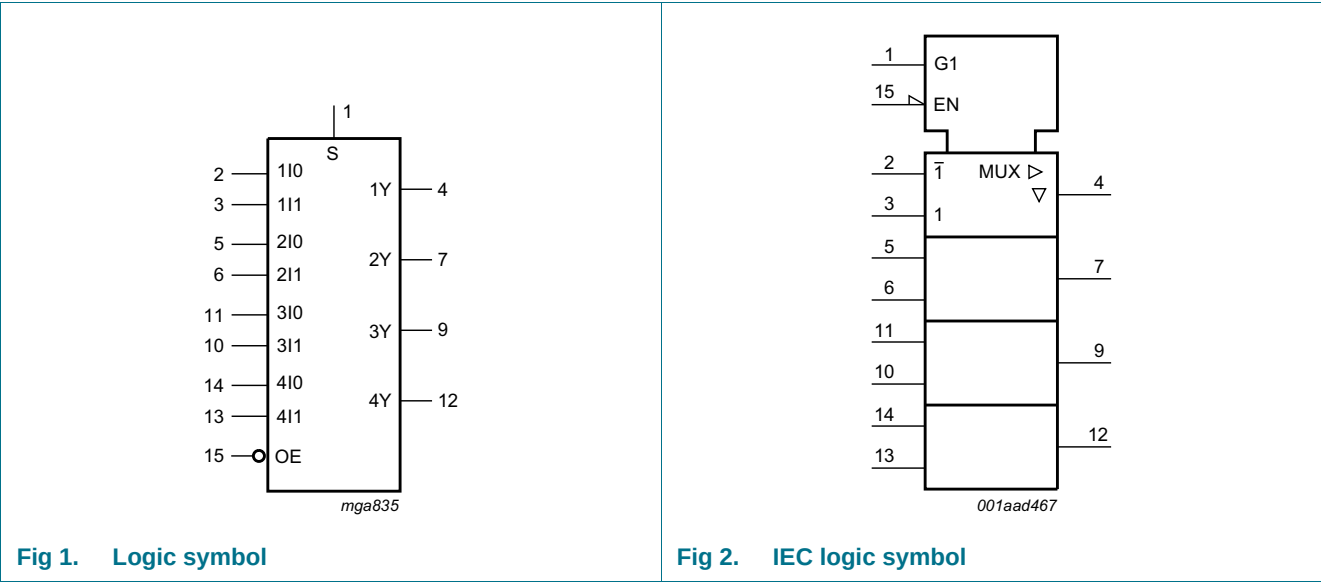


3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC257N	-40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT257N				
74HC257D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT257D				
74HC257DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT257DB				
74HC257PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT257PW				

4. Functional diagram



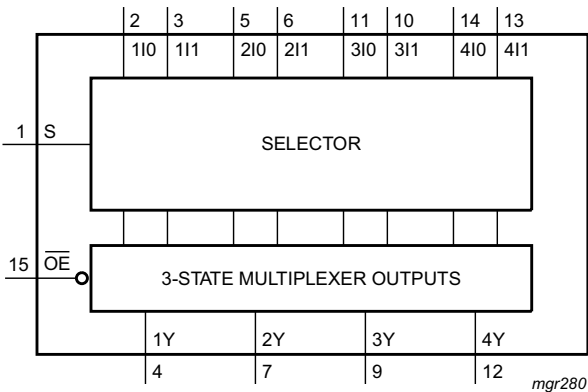


Fig 3. Functional diagram

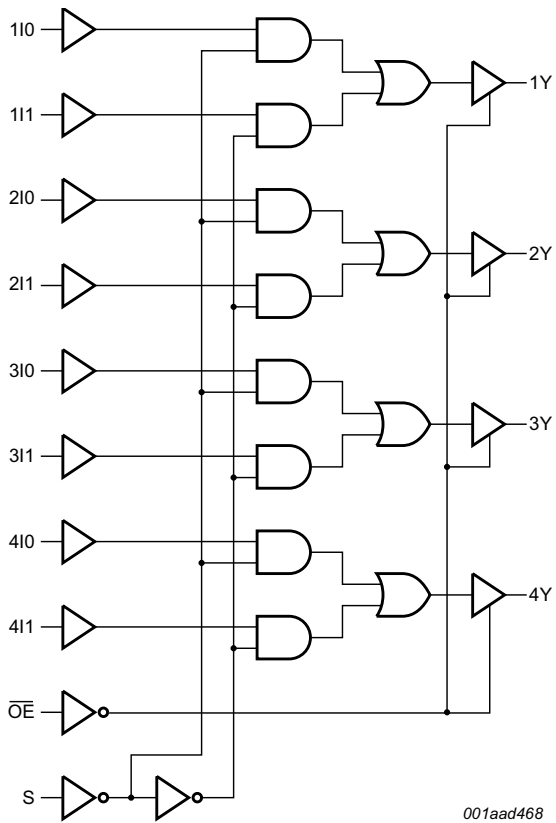


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning

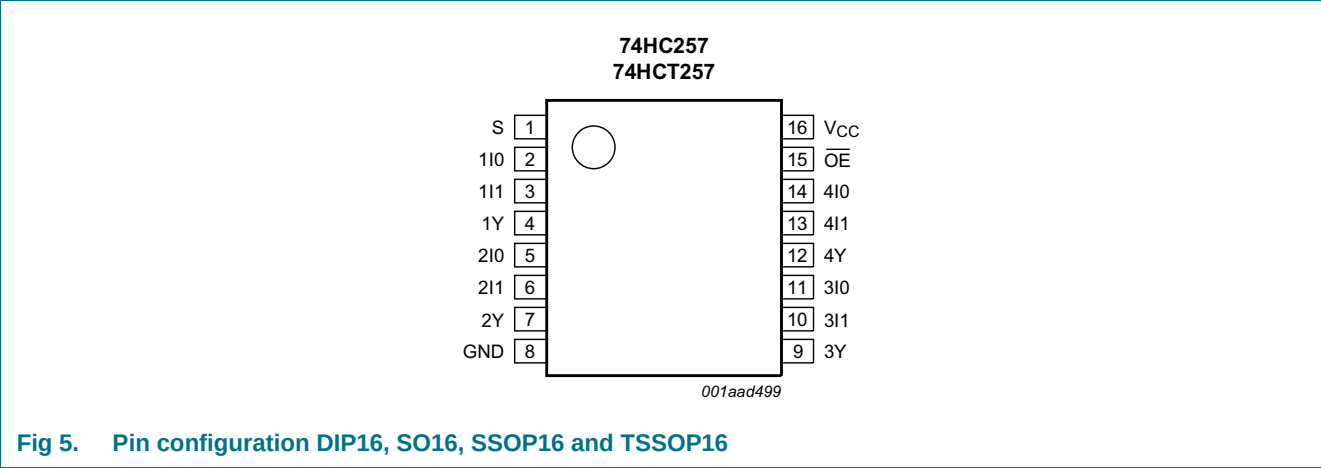


Fig 5. Pin configuration DIP16, SO16, SSOP16 and TSSOP16

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
S	1	common data select input
1I0 to 4I0	2, 5, 11, 14	data input from source 0
1I1 to 4I1	3, 6, 10, 13	data input from source 1
1Y to 4Y	4, 7, 9, 12	3-state multiplexer output
GND	8	ground (0 V)
OE	15	3-state output enable input (active LOW)
VCC	16	supply voltage

6. Functional description

6.1 Function table

Table 3. Function table^[1]

Control		Input		Output
OE	S	nI0	nI1	nY
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7	V
I_{IK}	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-	± 20	mA
I_{OK}	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	-	± 20	mA
I_O	output current	$V_O = -0.5\text{ V}$ to $V_{CC} + 0.5\text{ V}$	-	± 35	mA
I_{CC}	supply current		-	+70	mA
I_{GND}	ground current		-	-70	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation				
		DIP16 package [1]	-	750	mW
		SO16 package [2]	-	500	mW
		SSOP16 package [3]	-	500	mW
		TSSOP16 package [3]	-	500	mW

[1] For DIP16 packages: above 70 °C, P_{tot} derates linearly with 12 mW/K.

[2] For SO16 packages: above 70 °C, P_{tot} derates linearly with 8 mW/K.

[3] For SSOP16 and TSSOP16 packages: above 60 °C, P_{tot} derates linearly with 5.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74HC257						
V_{CC}	supply voltage		2.0	5.0	6.0	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
$\Delta t/\Delta V$	input transition rise and fall rates	$V_{CC} = 2.0\text{ V}$	-	-	625	ns
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns
		$V_{CC} = 6.0\text{ V}$	-	-	83	ns
T_{amb}	ambient temperature		-40	-	+125	°C
74HCT257						
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
$\Delta t/\Delta V$	input transition rise and fall rates	$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns
T_{amb}	ambient temperature		-40	-	+125	°C

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC257										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = –20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = –20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = –20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = –6.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I _O = –7.8 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 6.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 7.8 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1.0	±1.0	±1.0	μA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.5	-	±5.0	±10.0	±10.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	160	160	μA
C _i	input capacitance		-	3.5	-					pF
74HCT257										
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = –20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = –6 mA	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V				-	0.1	-	0.1	
		I _O = 20 μA	-	0	0.1	-	0.33	-	0.4	V
		I _O = 6.0 mA	-	0.15	0.26	-	±1.0	-	±1.0	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.1	-	±5.0	-	±10	μA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 5.5$ V; $V_O = V_{CC}$ or GND per input pin; other inputs at V_{CC} or GND; $I_O = 0$ A	-	-	±0.5	-	80	-	160	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V	-	-	8.0					μA
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 2.1$ V; other inputs at V_{CC} or GND; $V_{CC} = 4.5$ V to 5.5 V; $I_O = 0$ A								
		per input pin; nI0, nI1 inputs	-	40	144	-	180	-	196	μA
		per input pin; $\overline{OE}$ input	-	135	486	-	608	-	662	μA
		per input pin; S input	-	70	252	-	315	-	343	μA
C_I	input capacitance		-	3.5	-					pF

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C		–40 °C to +85 °C	–40 °C to +125 °C	Unit
			Typ	Max	Max	Max	
74HC257							
t _{pd}	propagation delay	nI0 to nY or nI1 to nY; see Figure 6 ^[1]					
		V _{CC} = 2.0 V	36	110	140	165	ns
		V _{CC} = 4.5 V	13	22	28	33	ns
		V _{CC} = 5.0 V; C _L = 15 pF	11	-	-	-	ns
		V _{CC} = 6.0 V	10	19	24	28	ns
		S to nY; see Figure 6					
		V _{CC} = 2.0 V	47	150	190	225	ns
		V _{CC} = 4.5 V	17	30	38	45	ns
		V _{CC} = 5.0 V; C _L = 15 pF	14	-	-	-	ns
		V _{CC} = 6.0 V	14	26	33	38	ns
t _{en}	enable time	$\overline{OE}$ to nY; see Figure 7 ^[2]					
		V _{CC} = 2.0 V	33	150	190	225	ns
		V _{CC} = 4.5 V	12	30	38	45	ns
		V _{CC} = 6.0 V	10	26	33	38	ns
t _{dis}	disable time	$\overline{OE}$ to nY; see Figure 7 ^[3]					
		V _{CC} = 2.0 V	41	150	190	225	ns
		V _{CC} = 4.5 V	15	30	38	45	ns
		V _{CC} = 6.0 V	12	26	33	38	ns

Table 7. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C		–40 °C to +85 °C	–40 °C to +125 °C	Unit
			Typ	Max	Max	Max	
t _t	transition time	see Figure 6 [4]					
		V _{CC} = 2.0 V	14	60	75	90	ns
		V _{CC} = 4.5 V	5	12	15	18	ns
		V _{CC} = 6.0 V	4	10	13	15	ns
C _{PD}	power dissipation capacitance	per multiplexer; V _I = GND to V _{CC} [5]	45	-			pF
74HCT257							
t _{pd}	propagation delay	nI0 to nY or nI1 to nY; see Figure 6 [1]					
		V _{CC} = 4.5 V	16	30	38	45	ns
		V _{CC} = 5.0 V; C _L = 15 pF	13	-	-		ns
		S to nY; see Figure 6					
		V _{CC} = 4.5 V	20	35	44	53	ns
		V _{CC} = 5.0 V; C _L = 15 pF	17	-			ns
t _{en}	enable time	$\overline{\text{OE}}$ to nY; V _{CC} = 4.5 V; see Figure 7 [2]	15	30	38	45	ns
t _{dis}	disable time	$\overline{\text{OE}}$ to nY; V _{CC} = 4.5 V; see Figure 7 [3]	16	30	38	45	ns
t _t	transition time	V _{CC} = 4.5 V; see Figure 6 [4]	5	12	15	18	ns
C _{PD}	power dissipation capacitance	per multiplexer; V _I = GND to V _{CC} – 1.5 V [5]	45	-			pF

[1] t_{pd} is the same as t_{PHL}, t_{PLH}.

[2] t_{en} is the same as t_{PZH}, t_{PZL}.

[3] t_{dis} is the same as t_{PHZ}, t_{PLZ}.

[4] t_t is the same as t_{THL}, t_{TLH}.

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

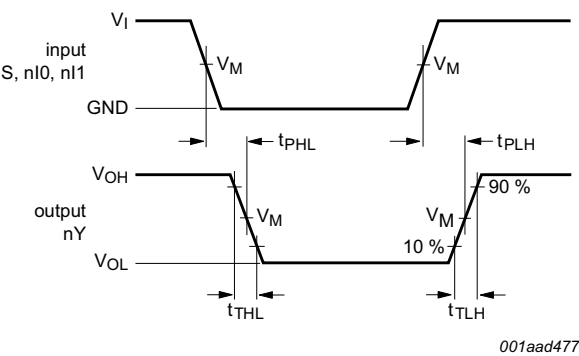
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

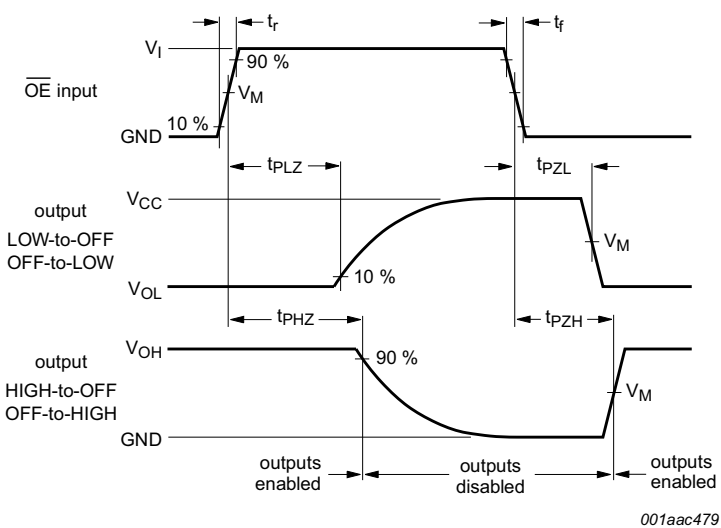
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Propagation delays input (S, nI0, nI1) to output (nY) and output (nY) transition times



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 7. 3-state output enable and disable times

Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74HC257	$0.5V_{CC}$	$0.5V_{CC}$
74HCT257	1.3 V	1.3 V

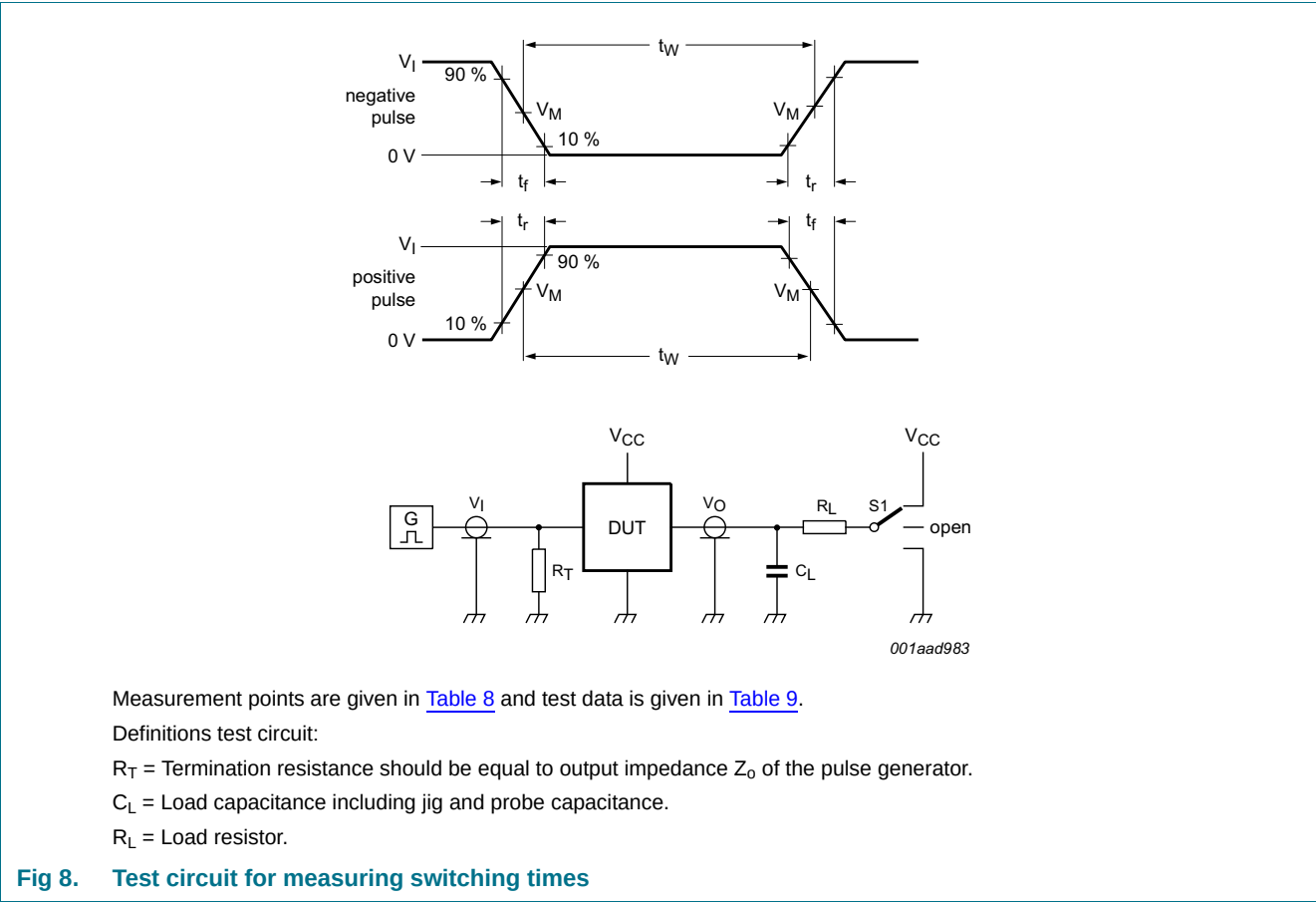


Table 9. Test data

Type	Input		Load		Switch position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC257	V_{CC}	6 ns	50 pF	1 k Ω	open	GND	V_{CC}
74HCT257	3 V	6 ns	50 pF	1 k Ω	open	GND	V_{CC}

12. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

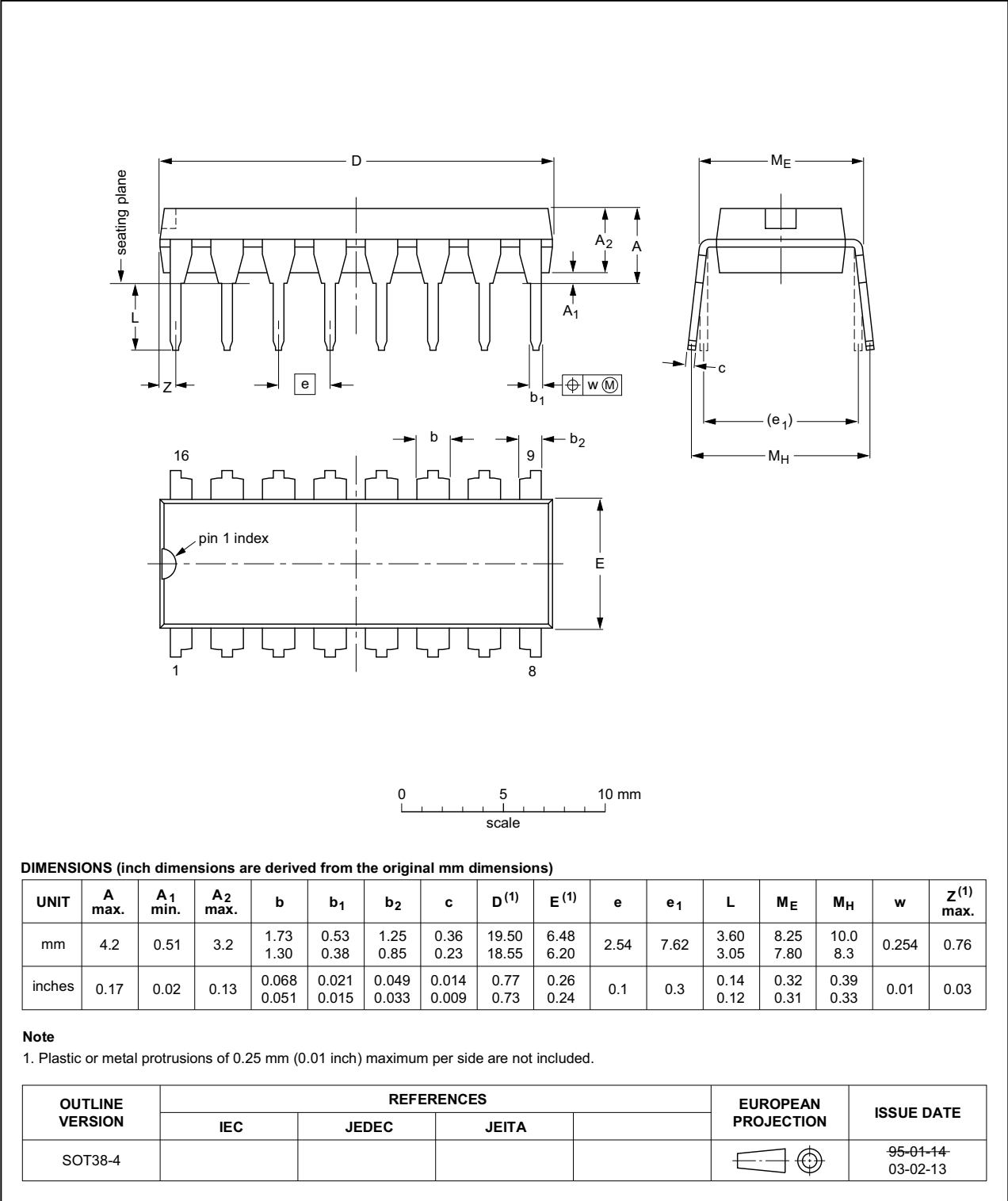


Fig 9. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

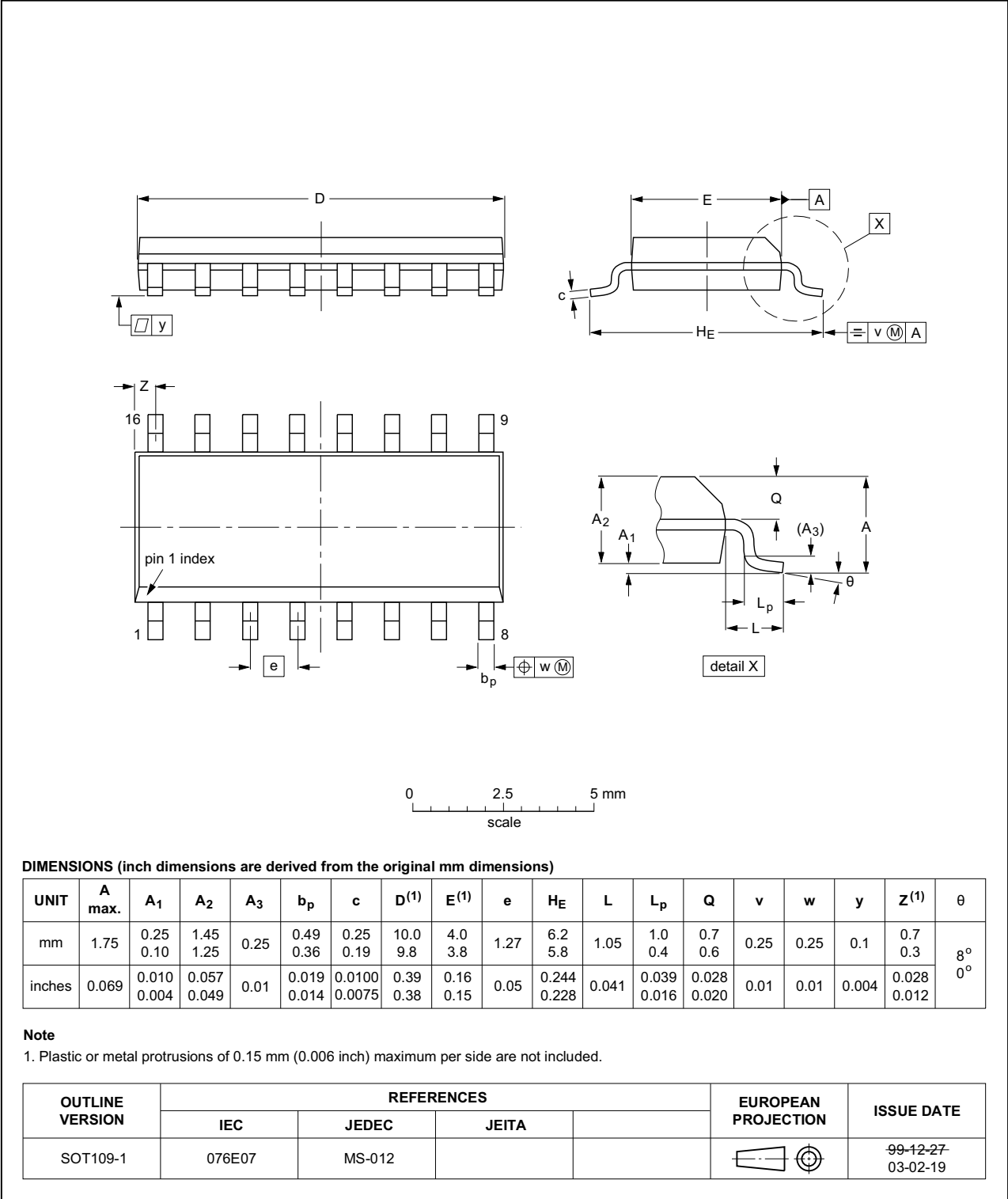


Fig 10. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

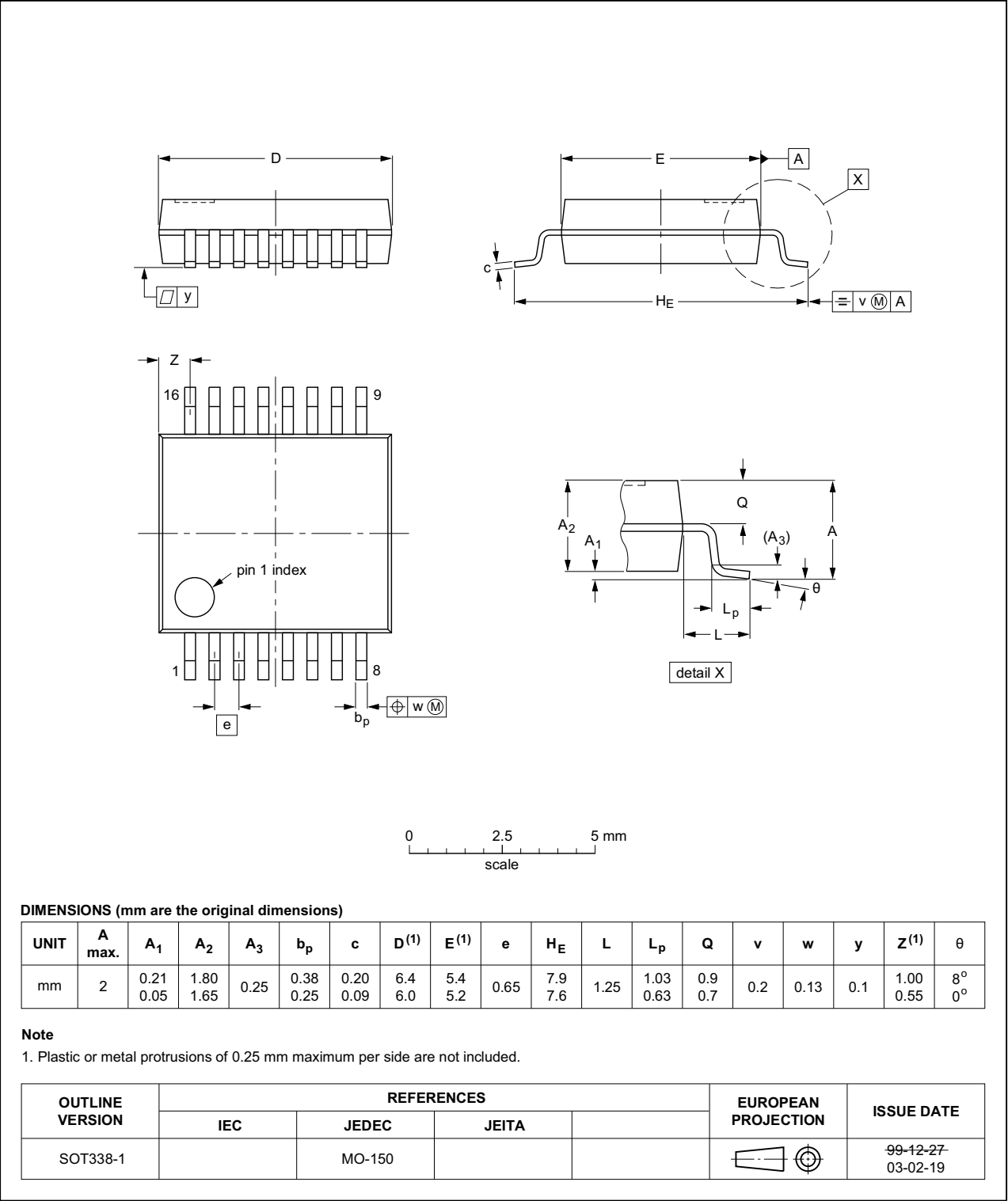


Fig 11. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

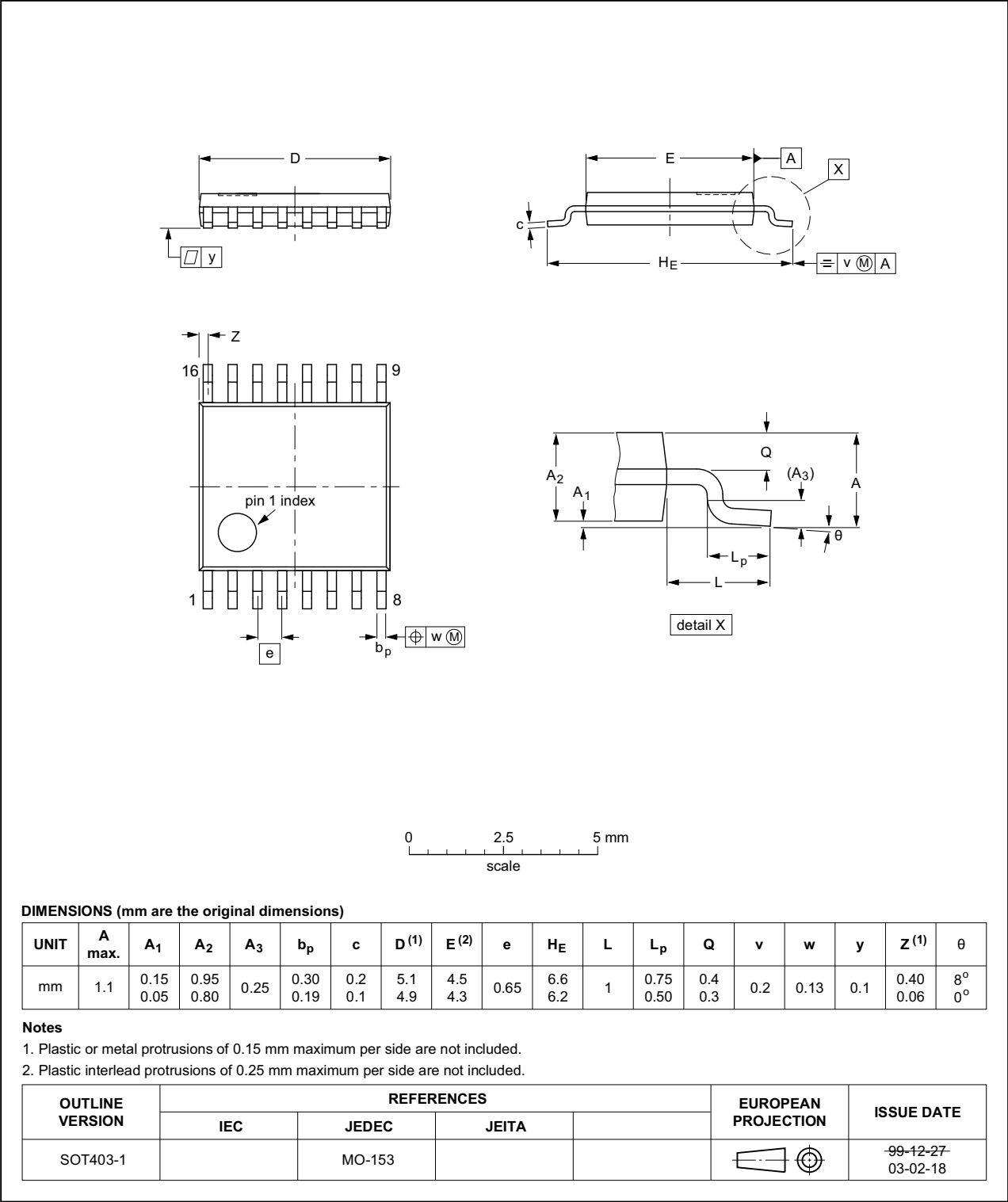


Fig 12. Package outline SOT403-1 (TSSOP16)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT257 v.6	20150126	Product data sheet	-	74HC_HCT257 v.5
Modifications:	• Table 7 : Power dissipation capacitance condition for 74HCT257 is corrected.			
74HC_HCT257 v.5	20100113	Product data sheet	-	74HC_HCT257 v.4
Modifications:	• Table 7 : changed $\overline{3OE}$ to $\overline{OE}$			
74HC_HCT257 v.4	20090608	Product data sheet	-	74HC_HCT257 v.3
74HC_HCT257 v.3	20050920	Product data sheet	-	74HC_HCT257_CNV v.2
74HC_HCT257_CNV v.2	19980930	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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